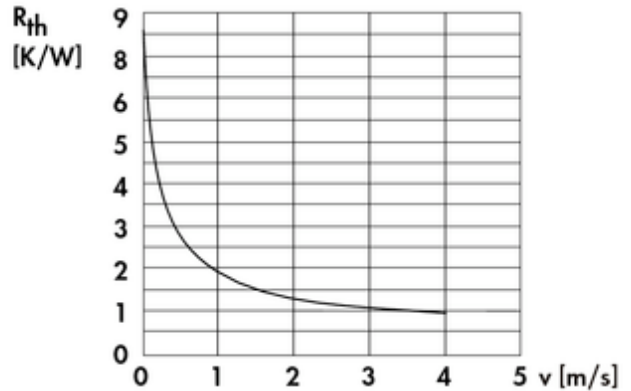
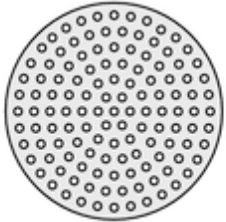
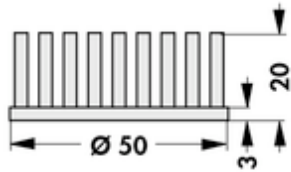
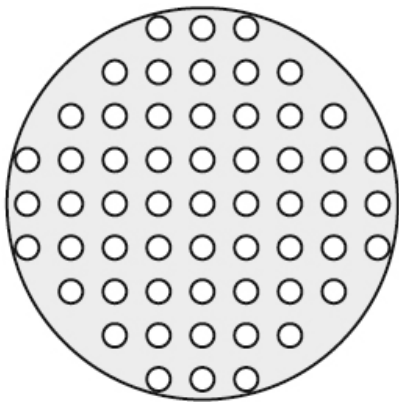


Pin heatsinks / **ICK S R 50 x 20**



Ø 50 x 20 mm, pin heatsinks round

Parameters of article ICK S R 50 x 20

Bauform	Rund
R_{th} [K/W]	8.55
dissipation loss [W]	9.8
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
Ø [mm]	50
height [mm]	20
plate thickness [mm]	3
weight [g]	34.39

Accessories/ related articles

- Thermally conductive foil both sides adhesive / **WLFT 404 D 50**
- Thermally conductive foil both sides adhesive / **WLFT 405 D 50**